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FEATURES

- Internal LDO allows single 16V operation
- Output Voltage Range: 0.5V to 0.875*P_{Vin}
- 0.5% accurate Reference Voltage
- Intel VR12.5 (Rev 1.5); VR13 (Rev 1.0) and SVID (Rev 1.7) compliant
- Enhanced line/load regulation with Feedforward
- Frequency programmable by PMBus up to 1.5 MHz
- Enable input with Voltage Monitoring Capability
- Remote Sense Amplifier with True Differential Voltage Sensing
- Fast mode I2C and 400 kHz PMBus interface for programming, sequencing and margining output voltage, and for monitoring input voltage, output voltage, output current and temperature.
- PMBus configurable fault thresholds for input UVLO, output OVP, OCP and thermal shutdown.
- Thermally compensated pulse-by-pulse current limit and Hiccup Mode Over Current Protection
- Dedicated output voltage sensing for power good indication and overvoltage protection which remains active even when Enable is low.
- Enhanced Pre-Bias Start up
- Integrated MOSFET drivers and Bootstrap diode
- Operating junction temp: -40°C < T_j < 125°C
- Thermal Shut Down
- Post Package trimmed rising edge dead-time
- PMBus Programmable Power Good Output
- Small Size 5mmx7mm PQFN
- Pb-Free (RoHS Compliant)
- External resistor allows setting up to 16 PMBus addresses

DESCRIPTION

This family of OPTIMOS IPOL devices offers easy-to-use, fully integrated and highly efficient DC/DC regulators with Intel SVID and I2C/PMBus interface. The on-chip PWM controller and co-packaged low duty cycle optimized MOSFETs make these devices a space-efficient solution, providing accurate power delivery for low output voltage and high current applications that require an Intel SVID interface.

These versatile devices offer programmability of switching frequency, output voltage, and fault/warning thresholds and fault responses while operating over a wide input range. Thus, they offer flexibility as well as system level security in event of fault conditions.

The switching frequency is programmable from 150 kHz to 1.5 MHz.

The on-chip sensors and ADC along with the SVID and PMBus interfaces (IR18163 and IR38363) or SVID and I2C interfaces (IR38165 and IR38365) make it easy to monitor and report input voltage, output voltage, output current and temperature.

APPLICATIONS

- Intel® VR13 and VR12.5 based systems
- Servers and High End Desktop CPU VRs for non-core applications

BASIC APPLICATION

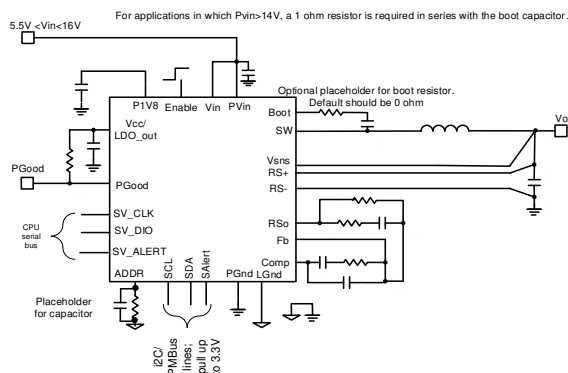


Figure 1: Typical application circuit

PIN DIAGRAM

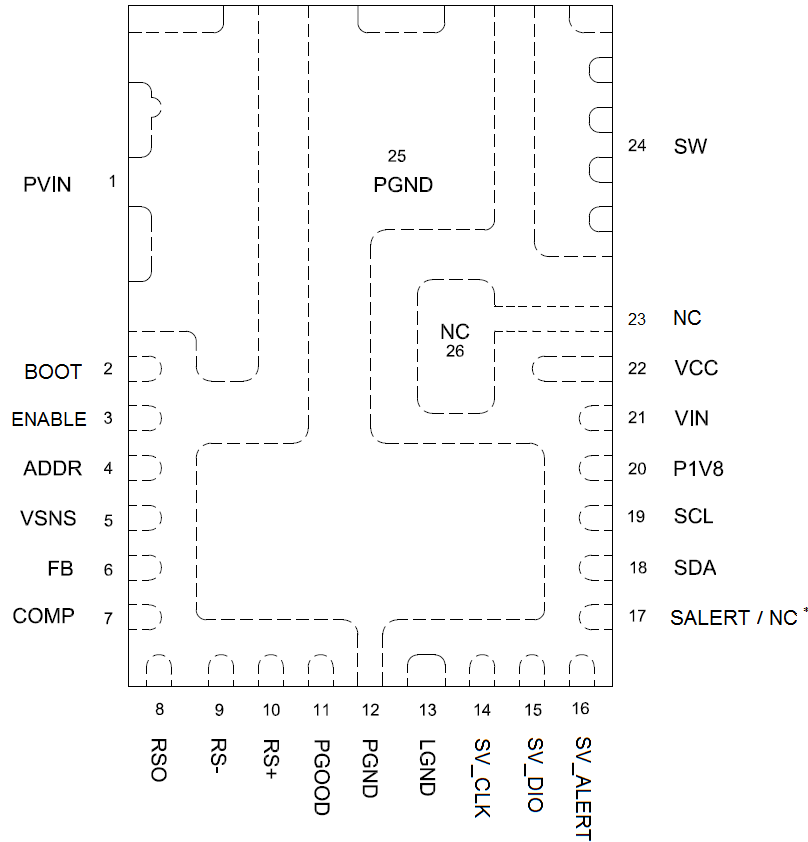


Figure 2: IR38163/363/165/365 Package Top View
5mm X 7mm PQFN

*IR38165 and IR38365 do not support PMBus and pin 17 is a no connect (NC)

ORDERING INFORMATION

Package	Tape and Reel Qty	Part Number	Description
PQFN	4000	IR38163MTRPbF	30A Buck Regulator with SVID and PMBus for Vccio
PQFN	4000	IR38363MTRPbF	15A Buck Regulator with SVID and PMBus for Vmcp
PQFN	4000	IR38165MTRPbF	30A Buck Regulator with SVID for Vccio
PQFN	4000	IR38365MTRPbF	15A Buck Regulator with SVID for Vmcp

FUNCTIONAL BLOCK DIAGRAM

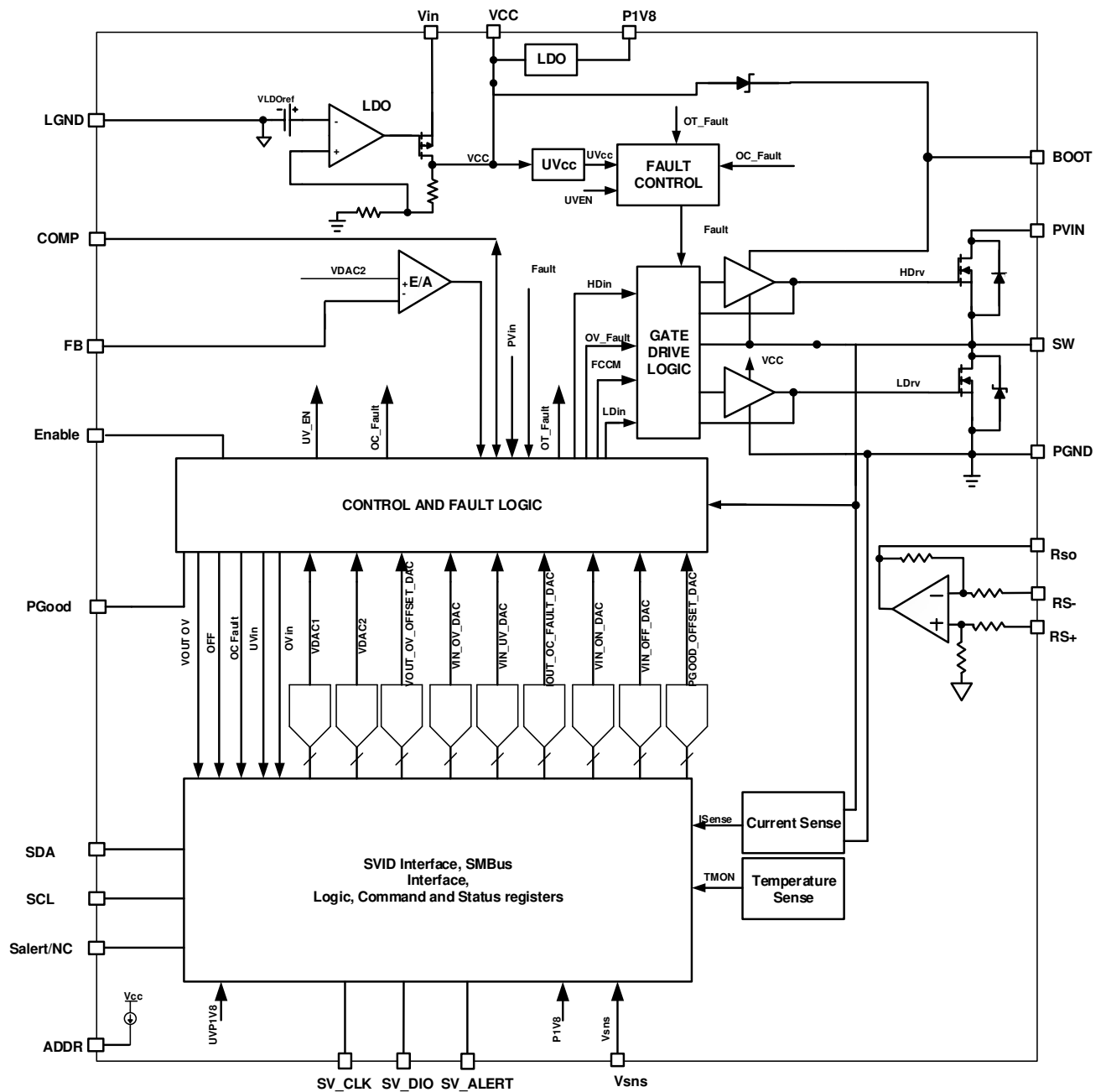


Figure 3: Simplified Block Diagram for IR38163/IR38363/IR38165/IR38365

PIN DESCRIPTIONS

PIN #	PIN NAME	PIN DESCRIPTION
1	PVIN	Input voltage for power stage. Bypass capacitors between PVin and PGND should be connected very close to this pin and PGND. Typical applications use four 22 uF input capacitors and a low ESR, low ESL 0.1uF decoupling capacitor in a 0603/0402 case size. A 3.3nF capacitor may also be used in parallel with these input capacitors to reduce ringing on the Sw node.
2	Boot	Supply voltage for high side driver. A 0.1uF capacitor should be connected from this pin to the Sw pin. It is recommended to provide a placement for a 0 ohm resistor in series with the capacitor. For applications in which PVin>14V, a 1 ohm resistor is required in series with boot capacitor.
3	ENABLE	Enable pin to turn on and off the IC
4	ADDR	A resistor should be connected from this pin to LGnd to set the PMBus address offset for the device. It is recommended to provide a placement for a 10 nF capacitor in parallel with the offset resistor.
5	Vsns	Sense pin for OVP and PGood. Typically connected to a local Vout capacitor at the output of the inductor.
6	FB	Inverting input to the error amplifier. This pin is connected directly to the output of the regulator or to the output of the remote sense amplifier, via resistor divider to set the output voltage and provide feedback to the error amplifier.
7	COMP	Output of error amplifier. An external resistor and capacitor network is typically connected from this pin to FB to provide loop compensation.
8	RSo	Remote Sense Amplifier Output. When the remote sense amplifier is used, this is connected to the feedback compensation network
9	RS-	Remote Sense Amplifier input. Connect to ground at the load.
10	RS+	Remote Sense Amplifier input. Connect to output at the load.
11	PGood	Power Good status pin. Output is open drain. Connect a pull up resistor from this pin to VCC. If the power good voltage before VCC UVLO needs to be limited to < 500 mV, use a 49.9K pullup, otherwise a 4.99K pullup will suffice.
12,25	PGND	Power ground. This pin should be connected to the system's power ground plane. Bypass capacitors between PVin and PGND should be connected very close to PVIN pin (pin 1) and this pin.
13	LGND	Signal ground for internal reference and control circuitry. This should be connected to the PGnd plane at a quiet location using a single point connection.
14	SV_CLK	SVID CLK line. This is pulled up to VDDIO/VCCIO voltage. It is recommended to provide a placement for a 0603 resistor between the pin and the pullup resistor
15	SV_DIO	SVID Data line. This is pulled up to VDDIO/VCCIO voltage. It is recommended to provide a placement for a 0603 resistor between the pin and the pullup resistor
16	SV_ALERT	SVID Alert line. This is pulled up to VDDIO/VCCIO voltage through a resistor.
17	SAlert#/NC	SMBus Alert line; open drain SMBALERT# pin. This should be pulled up to 3.3V-5V with a 1K-5K resistor. For IR38165 and IR38365, this a no connect pin.
18	SDA	SMBus data serial input/output line. This should be pulled up to 3.3V-5V with a 1K-5K resistor

PIN #	PIN NAME	PIN DESCRIPTION
19	SCL	SMBus clock line. This should be pulled up to 3.3V-5V with a 1K-5K resistor
20	P1V8	This is the supply for the digital circuits; bypass with a 10uF capacitor to PGnd. A 2.2uF capacitor is valid however a 10uF capacitor is recommended.
21	Vin	Input Voltage for LDO. A 1 uF capacitor is placed from this pin to PGnd. If the internal bias LDO is used, tie this pin to PVin. If an external bias voltage (typically 5V) is available for Vcc, tie the Vin pin to Vcc.
22	VCC	Bias Voltage for IC and driver section, output of LDO. Add 10 uF bypass cap from this pin to PGnd.
23,26	NC	NC
24	SW	Switch node. This pin is connected to the output inductor.

ABSOLUTE MAXIMUM RATINGS

Stresses beyond these listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied.

PVin, Vin	-0.3V to 25V
VCC	-0.3V to 6V
P1V8	-0.3V to 2 V
SW	-0.3V to 25V (DC), -4V to 25V (AC, 100ns)
BOOT	-0.3V to 31V
BOOT to SW	-0.3V to 6V (DC) (Note 1), -0.3V to 6.5V (AC, 100ns)
PGD, other Input/output pins	-0.3V to 6V (Note 1)
PGND to GND, RS- to GND	-0.3V to + 0.3V
THERMAL INFORMATION	
Junction to Ambient Thermal Resistance Θ_{JA}	11.1 C/W (Note 2)
Junction to case top Thermal Resistance $\theta_{JC(top)}$	18.9 C/W (Note 3)
Junction to PCB Thermal Resistance Θ_{JB}	4.16 C/W (Note 4)
Junction to case top parameter $\Psi_{JT(top)}$	0.32 C/W (Note 2)
Storage Temperature Range	-55°C to 150°C
Junction Temperature Range	-40°C to 150°C

(Voltages referenced to GND unless otherwise specified)

Note 1: Must not exceed 6V.

Note 2: Value obtained via thermal simulation under natural convention on a VCCIO demo board.

10 layer, 7"x5.5"x0.072" PCB with 1.5 oz copper at the top and bottom layer. Inner layers 2, 3, 8 and 9 have 1 oz copper and layers 4,5,6,7 have 2 oz copper. Ta = 25°C was used for the simulation.

Note 3: PCB from note 2 and package is considered in thermal simulation with Ta=25 °C. Pin 12 is considered.

Note 4: Only package is considered. Simulation is used with a cold plate that fixes top of package at Ta=25 °C.

ELECTRICAL SPECIFICATIONS

RECOMMENDED OPERATING CONDITIONS

SYMBOL	DEFINITION	MIN	MAX	UNITS
PVin	Input Bus Voltage	1.5	16*	V
Vin	LDO supply voltage	5.3	16	
VCC	LDO output/Bias supply voltage	4.5	5.5	
Boot to SW	High Side driver gate voltage	4.5	5.5	
VO	Output Voltage	0.5	0.875*PV _{in}	
I _o	Output Current	0	30	A
Fs	Switching Frequency	150	1500	kHz
T _J	Junction Temperature	-40	125	°C

* SW Node must not exceed 25V

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
MOSFET R_{ds(on)}						
Top Switch	Rds(on)_Top	V _{Boot} – V _{SW} = 5V, I _D = 30A, T _j = 25°C		2.2		mΩ
Bottom Switch	Rds(on)_Bot	V _{cc} =5V, I _D = 30A, T _j = 25°C		0.78		
Reference Voltage						
Accuracy 0°C<T _j <85°C		1.25V<V _{FB} <2.555V VOUT_SCALE_LOOP=1;	-1		+1	%
		0.75V<V _{FB} <1.25V VOUT_SCALE_LOOP=1;	-0.75		+0.75	%
		0.45V<V _{FB} <0.75V VOUT_SCALE_LOOP=1;	-0.5		+0.5	%
Accuracy -40°C<T _j <125°C		1.25V<V _{FB} <2.555V VOUT_SCALE_LOOP=1;	-1.6		+1.6	%
		0.75V<V _{FB} <1.25V VOUT_SCALE_LOOP=1;	-1.0		+1.0	%
		0.45V<V _{FB} <0.75V VOUT_SCALE_LOOP=1;	-2.0		+2.0	%
Supply Current						
PVin range (using external V _{cc} =5V)				1.5-16		V
Vin range (using internal LDO)		F _{sw} =600kHz		5.3-16		V
		F _{sw} =1.5MHz		5.5-		

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
				16		
V _{in} range (when V _{in} =V _{cc})			4.5	5.0	5.5	V
V _{in} Supply Current (Standby) (internal V _{cc})	I _{in(Standby)}	Enable low, No Switching, V _{in} =16V, low power mode enabled		2.7	4	mA
V _{in} Supply Current (Dyn)(internal V _{cc})	I _{in(Dyn)}	Enable high, F _s = 600kHz, V _{in} =16V		39	50	mA
V _{cc} Supply Current (Standby)(external V _{cc})	I _{cc(Standby)}	Enable low, No Switching, V _{cc} =5.5V, low power mode enabled		2.7	5	mA
V _{cc} Supply Current (Dyn)(external V _{cc})	I _{cc(Dyn)}	Enable high, F _s = 600kHz, V _{cc} =5.5V		39	50	mA
Under Voltage Lockout						
V _{cc} – Start – Threshold	VCC_UVLO_Start	V _{cc} Rising Trip Level	4.0	4.2	4.4	V
V _{cc} – Stop – Threshold	VCC_UVLO_Stop	V _{cc} Falling Trip Level	3.7	3.9	4.1	
Enable – Start – Threshold	Enable_UVLO_Start	Supply ramping up	0.55	0.6	0.65	V
Enable – Stop – Threshold	Enable_UVLO_Stop	Supply ramping down	0.35	0.4	0.45	
Enable leakage current	I _{en}	Enable=5.5V			1	µA
Oscillator						
Ramp Amplitude	V _{ramp}	PV _{in} =5V, D=D _{max} , Note 2		0.71		V _{p-p}
		PV _{in} =12V, D=D _{max} , Note 2		1.84		
		PV _{in} =16V, D=D _{max} , Note 2		2.46		
Ramp Offset	Ramp (os)	Note 2		0.22		V
Min Pulse Width	D _{min} (ctrl)	Note 2		35	50	ns
Fixed Off Time		Note 2 F _s =1.5MHz		100	150	ns
Max Duty Cycle	D _{max}	F _s =400kHz	86	87.5	89	%
Error Amplifier						
Input Bias Current	I _{Fb(E/A)}		-0.5		+0.5	µA
Sink Current	I _{sink(E/A)}		0.6	1.1	1.8	mA
Source Current	I _{source(E/A)}		8	13	25	mA
Slew Rate	SR	Note 2	7	12	20	V/µs
Gain-Bandwidth Product	GBWP	Note 2	20	30	40	MHz
DC Gain	Gain	Note 2	100	110	120	dB
Maximum Voltage	V _{max(E/A)}		2.8	3.9	4.3	V
Minimum Voltage	V _{min(E/A)}				100	mV
Remote Sense Differential Amplifier						

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Unity Gain Bandwidth	BW_RS	Note 2	3	6.4		MHz
DC Gain	Gain_RS	Note 2		110		dB
Offset Voltage	Offset_RS	0.5V<RS+<2.555V, 4kOhm load 27°C<Tj<85°C	-1.6	0	1.6	mV
		0.5V<RS+<2.555V, 4kOhm load -40°C<Tj<125°C	-3		3	
Source Current	Isource_RS	V_RSO=1.5V, V_RSP=4V	11		16	mA
Sink Current	Isink_RS		0.4	1	2	mA
Slew Rate	Slew_RS	Note 2, Cload = 100pF	2	4	8	V/μs
RS+ input impedance	Rin_RS+		36	55	74	Kohm
RS- input impedance	Rin_RS-	Note 2	36	55	74	Kohm
Maximum Voltage	Vmax_RS	V(VCC) – V(RS+)	0.5	1	1.5	V
Minimum Voltage	Min_RS			4	20	mV
Bootstrap Diode						
Forward Voltage		I(Boot) = 40mA	150	300	450	mV
Switch Node						
SW Leakage Current	Lsw	SW = 0V, Enable = 0V			1	μA
	lsw_En	SW=0; Enable= 2V		18		
Internal Regulator (VCC/LDO)						
Output Voltage	VCC	Vin(min) = 5.5V, Io=0mA, Cload = 10uF	4.8	5.15	5.4	V
		Vin(min) = 5.5V, Io=70mA, Cload = 10uF	4.5	4.99	5.2	
VCC dropout	VCC_drop	Io=0-70mA, Cload = 10uF, Vin=5.1V			0.7	V
Short Circuit Current	Ishort			110		mA
Internal Regulator (P1V8)						
Output Voltage	P1V8	Vin(min) = 4.5V, Io = 0-1mA, Cload = 2.2uF	1.795	1.83	1.905	V
1.8V UVLO Start	P1V8_UVLO_Start	1.8V Rising Trip Level	1.66	1.72	1.78	V
1.8V UVLO Stop	P1V8_UVLO_Stop	1.8V Falling Trip Level	1.59	1.63	1.68	V
Adaptive On time Mode						
Zero-crossing comparator threshold	ZC_Vth		-4	-1	2	mV
Zero-crossing comparator delay	ZC_Tdly			8/Fs		S
FAULTS						

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Power Good						
Power Good High threshold	Power_Good_High	Vsns rising, VOUT_SCALE_LOOP=1, Vout=0.5V, PMBus mode		0.45		V
Power Good Low Threshold	Power_Good_Low	Vsns falling, VOUT_SCALE_LOOP=1, Vout=0.5V, PMBus mode		0.43		V
Power Good High Threshold Rising Delay	TPDLY	Vsns rising, Vsns > Power_Good_High		0		ms
Power Good Low Threshold Falling delay	VPG_low_Dly	Vsns falling, Vsns < Power_Good_Low	150	175	200	μs
PGood Voltage Low	PG (voltage)	I _{PGood} = -5mA			0.5	V
Over Voltage Protection (OVP)						
OVP Trip Threshold	OVP (trip)	Vsns rising, VOUT_SCALE_LOOP=1, Vout=0.5V	0.57	0.60 5	0.63	V
OVP comparator Hysteresis	OVP (hyst)	Vsns falling, VOUT_SCALE_LOOP=1, Vout=0.5V	20	30	40	mV
OVP Fault Prop Delay	OVP (delay)	Vsns rising, Vsns-OVP(trip)>200 mV		200		ns
Over-Current Protection						
OC Trip Current	I _{TRIP} IR38163/165	OC limit=40, VCC = 5.05V, T _j =25°C	36	40	44	A
		OC limit=16A, VCC = 5.05V, T _j =25°C	12.5	16	19.5	A
	I _{TRIP} IR38363/365	OC limit=20A, VCC = 5.05V, T _j =25°C	16.5	20	23.5	A
		OC limit=16A, VCC = 5.05V, T _j =25°C	12.5	16	19.5	A
OCset Current Temperature coefficient	OCSET(temp)	-40°C to 125°C, VCC=5.05V, Note 2		5900		ppm/°C
Hiccup blanking time	T _{blk_Hiccup}	Note 2		20		ms
Thermal Shutdown						
Thermal Shutdown		Note 2		145		°C
Hysteresis		Note 2		25		°C
Input Over-Voltage Protection						
PVin overvoltage threshold	PVin _{ov}		22	23.7	25	V
PVin overvoltage Hysteresis	PVin _{ov hyst}			2.4		V
MONITORING AND REPORTING						

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Bus Speed ¹				100	400	kHz
I _{out} & V _{out} filter				78		Hz
I _{out} & V _{out} Update rate				31.2 5		kHz
V _{in} & Temperature filter				78		Hz
V _{in} & Temperature update rate				31.2 5		kHz
Output Voltage Reporting						
Resolution	N _{Vout}	Note 2		1/256		V
Lowest reported V _{out}	V _{omon_low}	V _{sns} =0V		0		V
Highest reported V _{out}	V _{omon_high}	VOUT_SCALE_LOOP=1, V _{sns} =3.3V		3.3		V
		VOUT_SCALE_LOOP=0.5, V _{sns} =3.3V		6.6		V
		VOUT_SCALE_LOOP=0.25, V _{sns} =3.3V		13.2		V
		VOUT_SCALE_LOOP=0.125 , V _{sns} =3.3V		26.4		V
V _{out} reporting accuracy		0°C to 85°C, 4.5V<V _{cc} <5.5V, 1V<V _{sns} ≤ 1.5V VOUT_SCALE_LOOP=1		+/- 0.6		%
		0°C to 85°C, 4.5V<V _{cc} <5.5V, V _{sns} > 1.5V VOUT_SCALE_LOOP=1		+/-1		
		0°C to 125°C, 4.5V<V _{cc} <5.5V, V _{sns} >0.9V VOUT_SCALE_LOOP=1		+/- 1.5		
		0°C to 125°C, 4.5V<V _{cc} <5.5V, 0.5V<V _{sns} <0.9V VOUT_SCALE_LOOP=1		+/-3		
I_{out} Reporting						
Resolution	N _{Iout}	Note 2		0.06 25		A
I _{out} (digital) monitoring Range	I _{out_dig} IR38163/165		0		40	A
	I _{out_dig} IR38363/365		0		20	A
I _{out_dig} Accuracy	IR38163/165 i2c/PMBus mode	0°C to 125°C, 4.5V<V _{cc} <5.5V, 5A < I _{out} <30A		+/-5		%
	IR38363/365 i2c/PMBus mode	0°C to 125°C, 4.5V<V _{cc} <5.5V, 5A < I _{out} <15A				

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
	SVID mode IR38163/165/363/365	0°C to 125°C, 4.5V<Vcc<5.5V	Intel VR13 spec	Intel VR1 3 spec	Intel VR13 spec	
Temperature Reporting						
Resolution	N _{Tmon}	Note 2		1		°C
Temperature Monitoring Range	T _{mon_dig}		-40		150	°C
Thermal shutdown hysteresis		Note 2		25		°C
Input Voltage Reporting						
Resolution	N _{Pvin}	Note 2		1/32		V
Monitoring Range	PMBVinmon		0		21	V
Monitoring accuracy		0°C to 85°C, 4.5V<Vcc<5.5V, PVin>10V	-1.5		1.5	%
		-40°C to 125°C, 4.5V<Vcc<5.5V, PVin>14V	-1.5		1.5	
		-40°C to 125°C, 4.5V<Vcc<5.5V, 7V<PVin<14V	-4		4	
PMBus Interface Timing Specifications						
SMBus Operating frequency	F _{SMB}				400	kHz
Bus Free time between Start and Stop condition	T _{BUF}		1.3			µs
Hold time after (Repeated) Start Condition. After this period, the first clock is generated.	T _{HD:STA}		0.6			µs
Repeated start condition setup time	T _{SU:STA}		0.6			µs
Stop condition setup time	T _{SU:STO}		0.6			µs
Data Rising Threshold			1.339		1.766	V
Data Falling Threshold			1.048		1.495	V
Clock Rising Threshold			1.339		1.766	V
Clock Falling Threshold			1.048		1.499	V
Data Rising Threshold LVT			0.7		0.9	V
Data Falling Threshold			0.45		0.65	V

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
LVT						
Clock Rising Threshold LVT			0.7		0.9	V
Clock Falling Threshold LVT			0.45		0.65	V
Data Hold Time	T _{HD:DAT}		300		900	ns
Data Setup Time	T _{SU:DAT}		100			ns
Data pulldown resistance			8	11	16	Ω
SALERT# pulldown resistance			9	12	17	Ω
Clock low time out	T _{TIMEOUT}		25		35	ms
Clock low period	T _{LOW}		1.3			μs
Clock High Period	T _{HIGH}		0.6		50	μs

Notes

2. Guaranteed by design but not tested in production
3. Guaranteed by statistical correlation, but not tested in production

TYPICAL APPLICATION DIAGRAMS

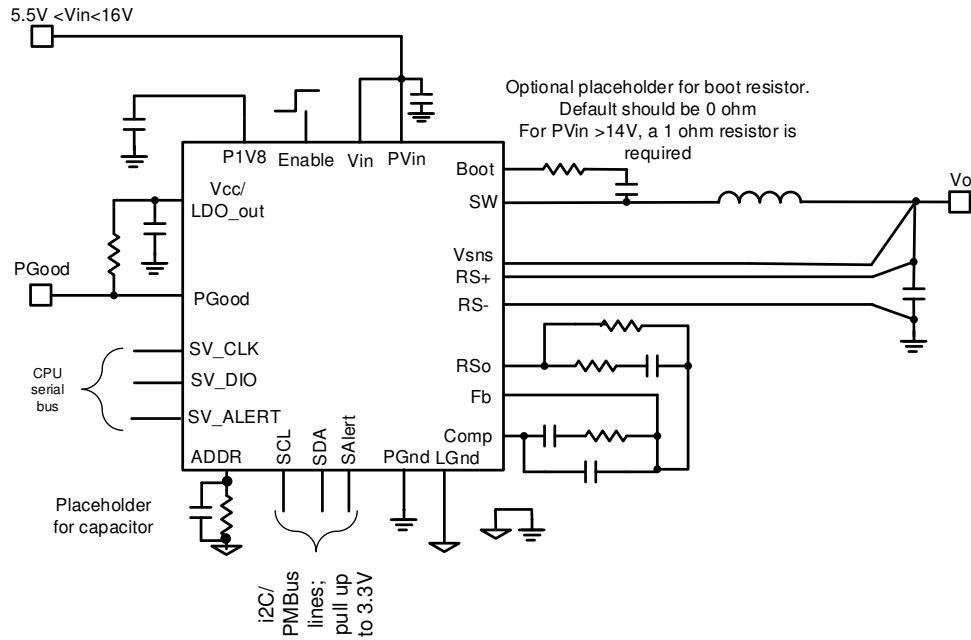


Figure 4: Using the internal LDO, $V_o < 2.555V$

For applications in which $P_{vin} > 14V$, a 1 ohm resistor is required in series with the boot capacitor.

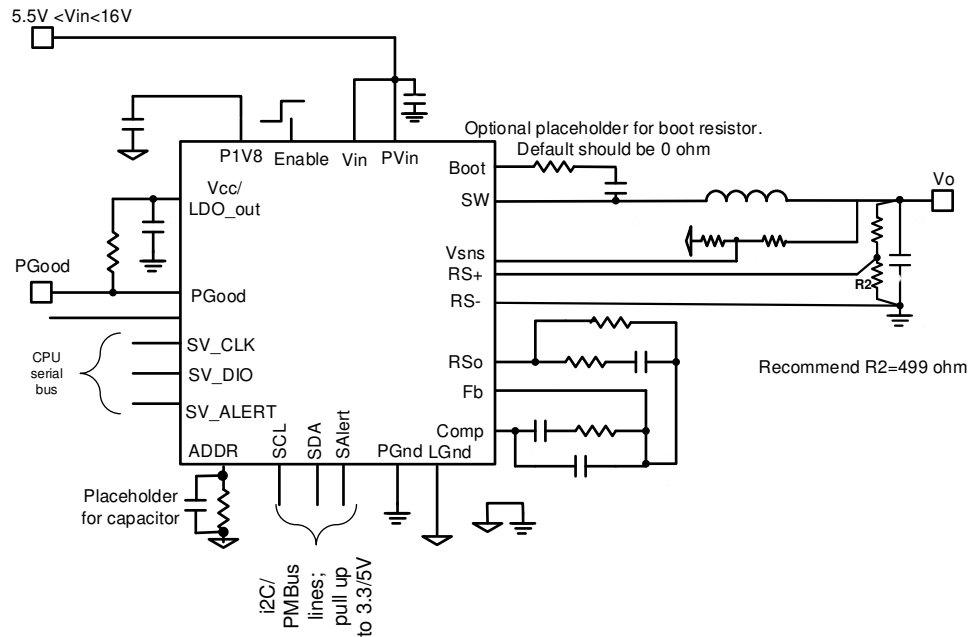


Figure 5: Using the internal LDO, $V_o > 2.555V$

TYPICAL APPLICATION DIAGRAMS

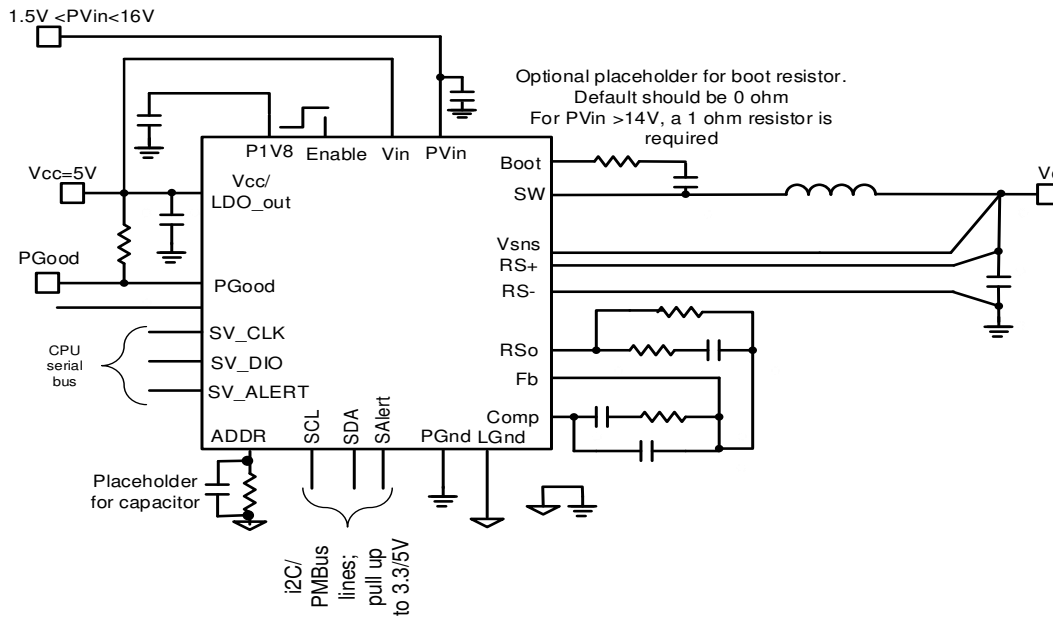


Figure 6: Using external Vcc, Vo<2.555V

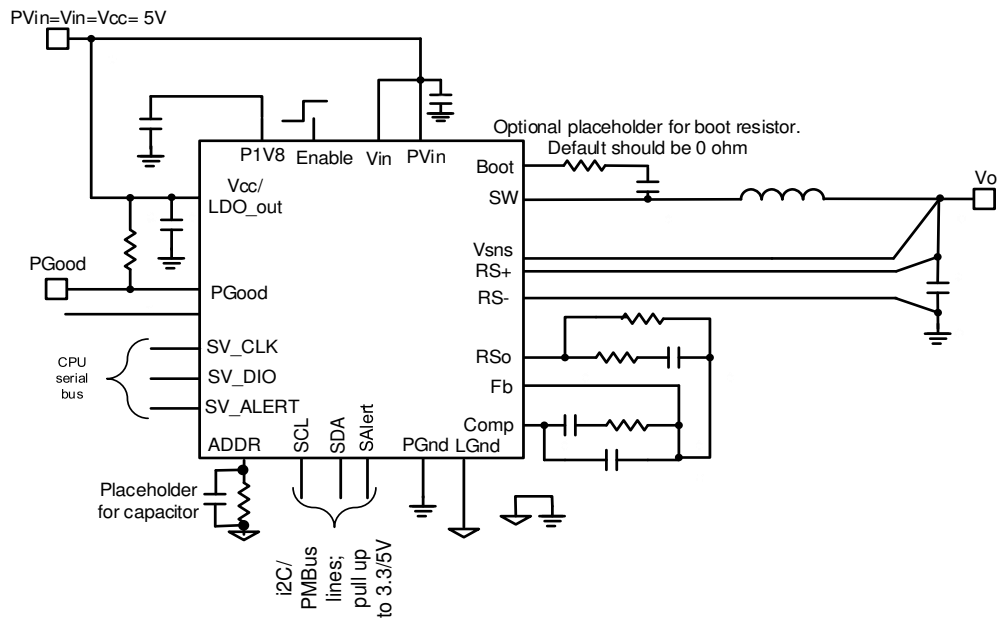
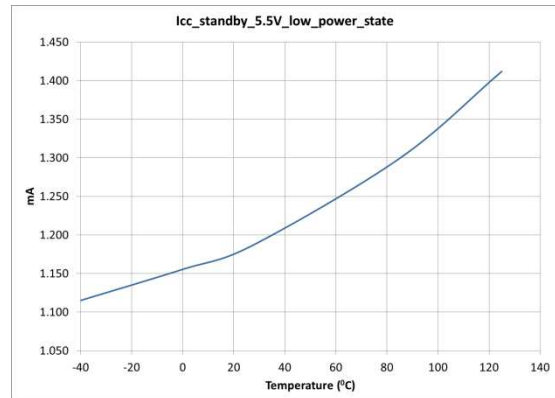
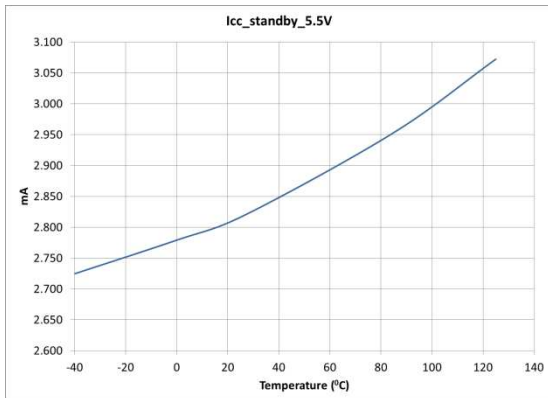
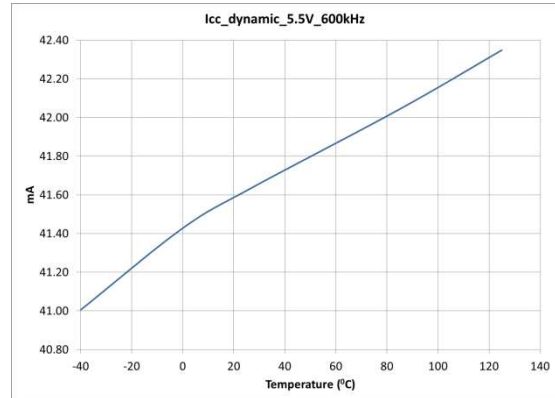
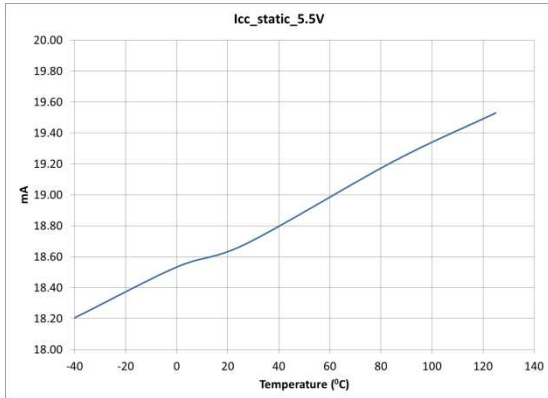
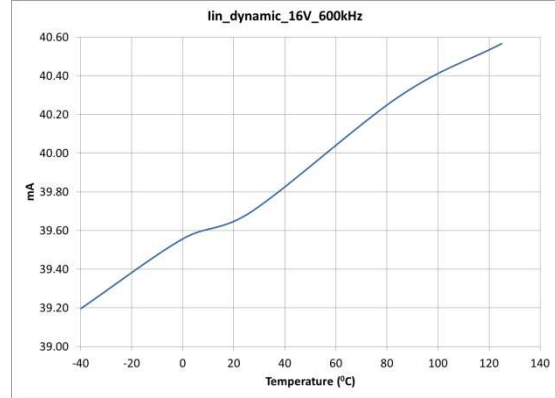
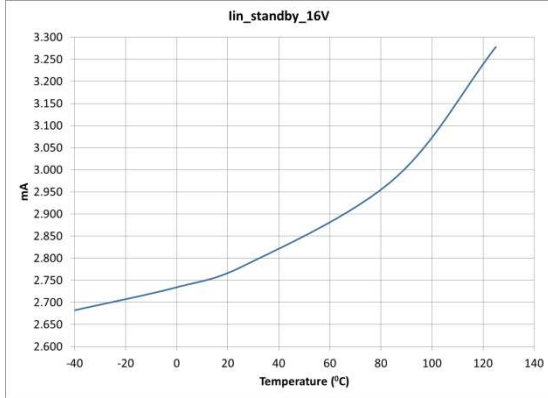
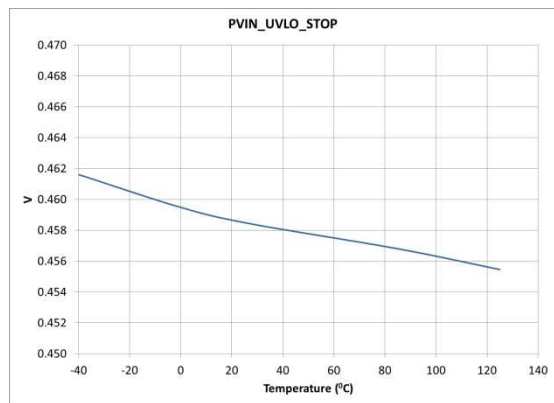
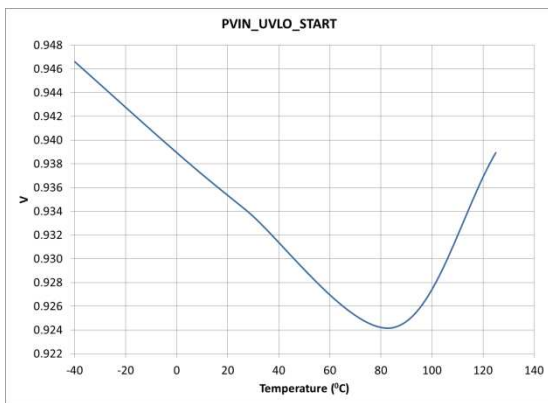
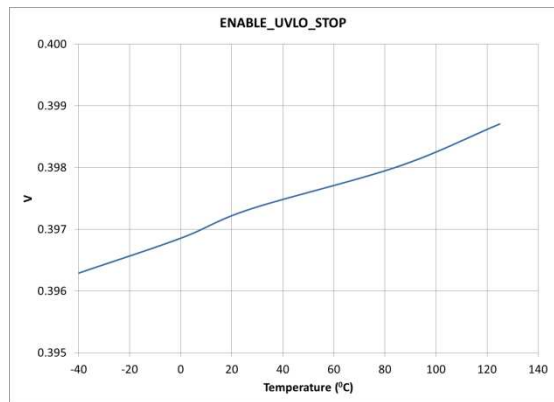
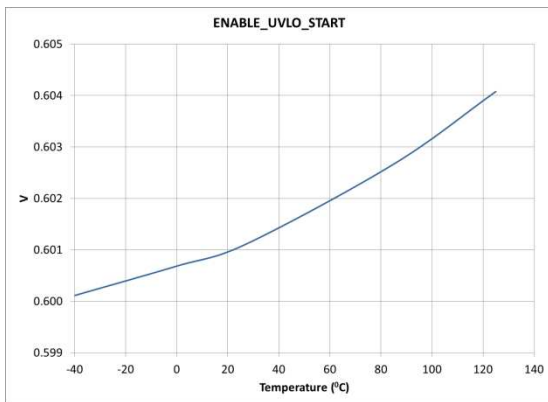
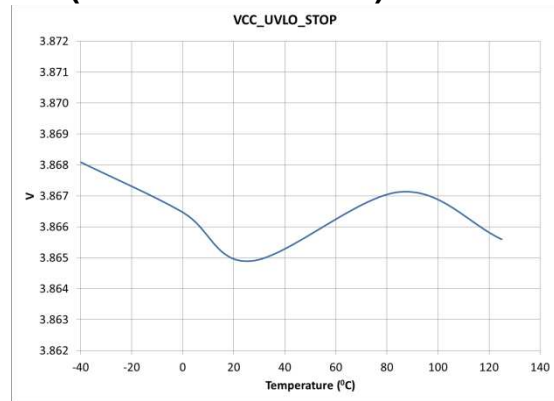
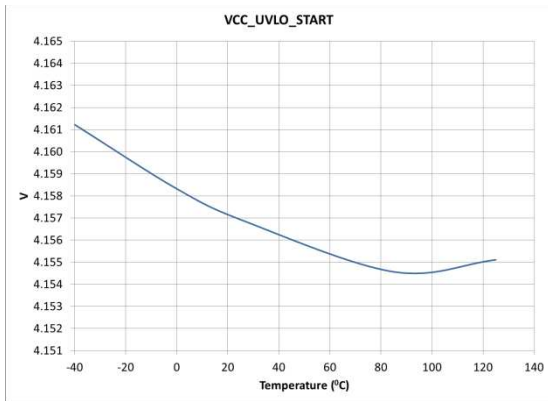


Figure 7: Single 5V application, Vo<2.555V

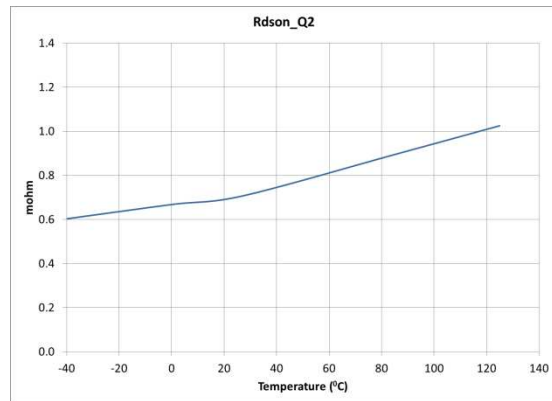
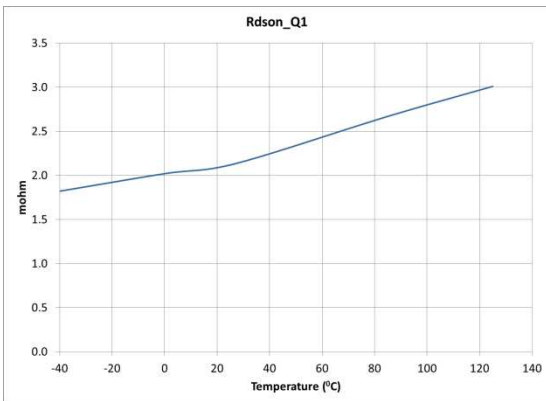
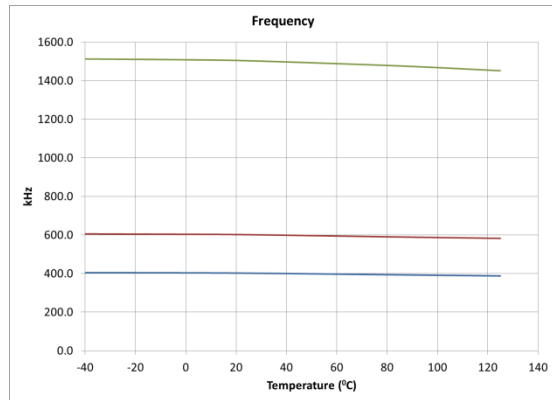
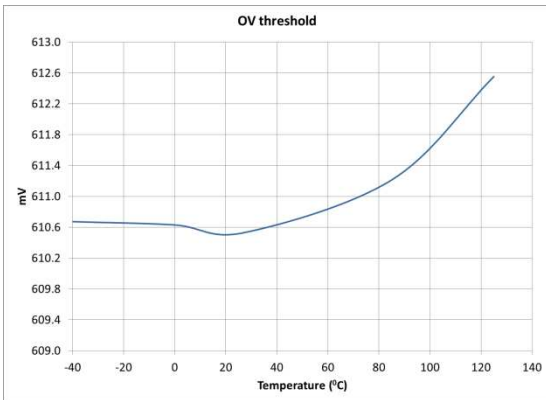
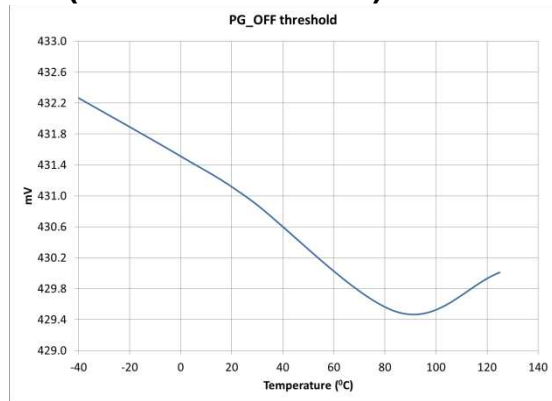
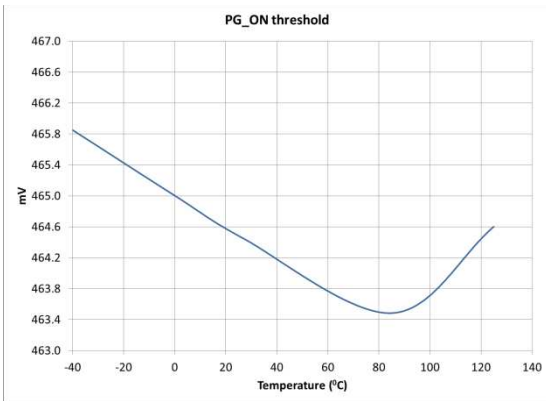
TYPICAL OPERATING CHARACTERISTICS (-40°C TO +125°C)



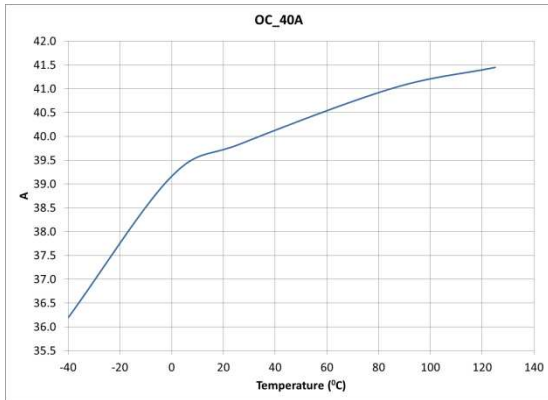
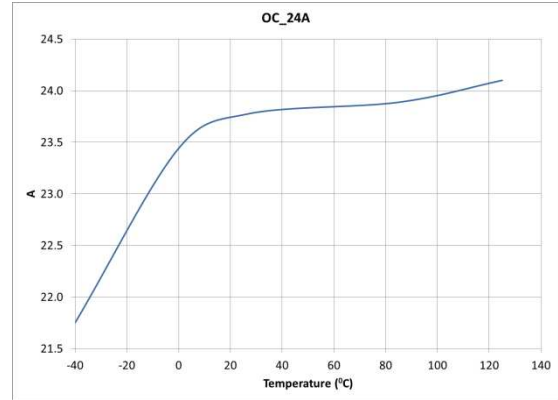
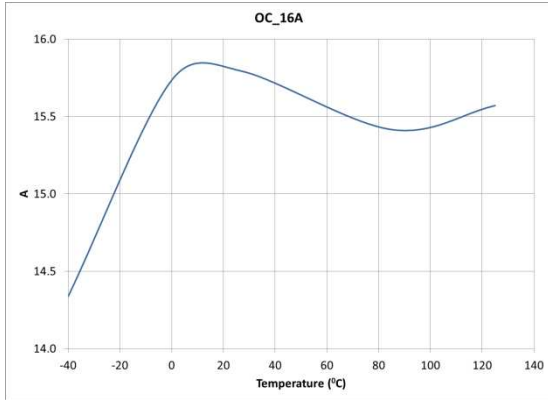
TYPICAL OPERATING CHARACTERISTICS (-40°C TO +125°C)



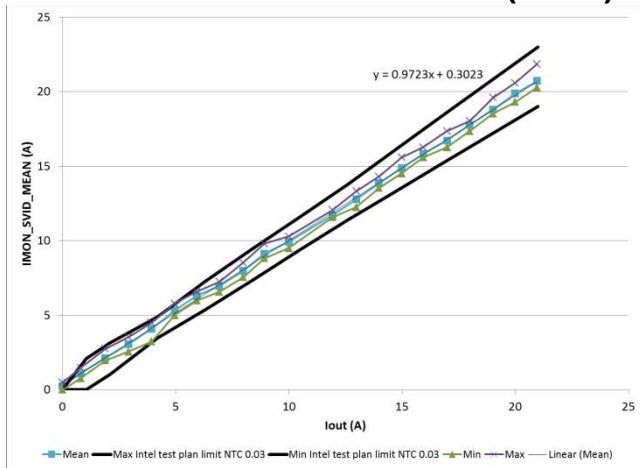
TYPICAL OPERATING CHARACTERISTICS (-40°C TO +125°C)



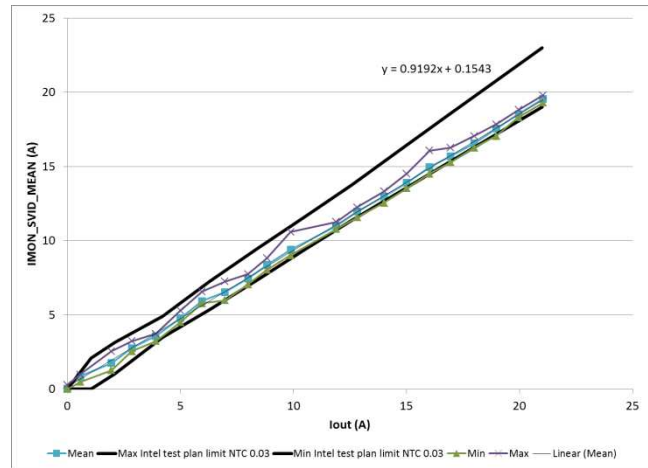
TYPICAL OPERATING CHARACTERISTICS (-40°C TO +125°C)



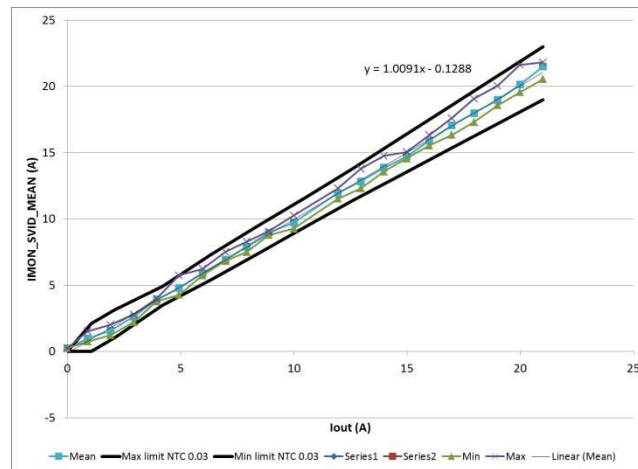
IOOUT REPORTING CURVES (SVID)



SVID readings with typical reporting gain



SVID readings with minimum reporting gain



SVID readings with maximum reporting gain

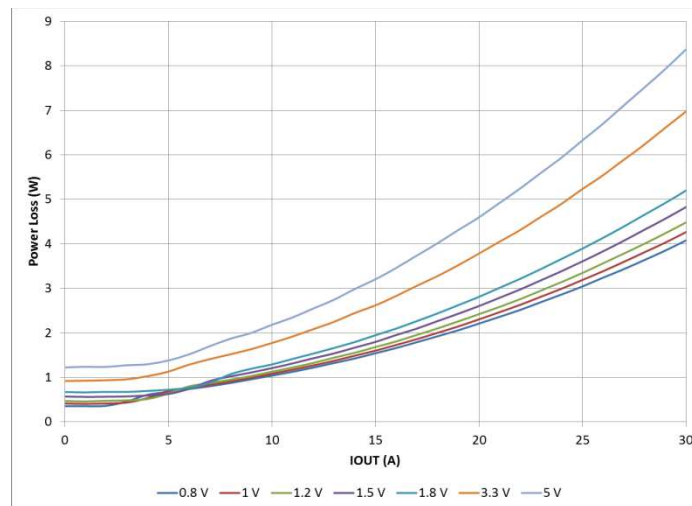
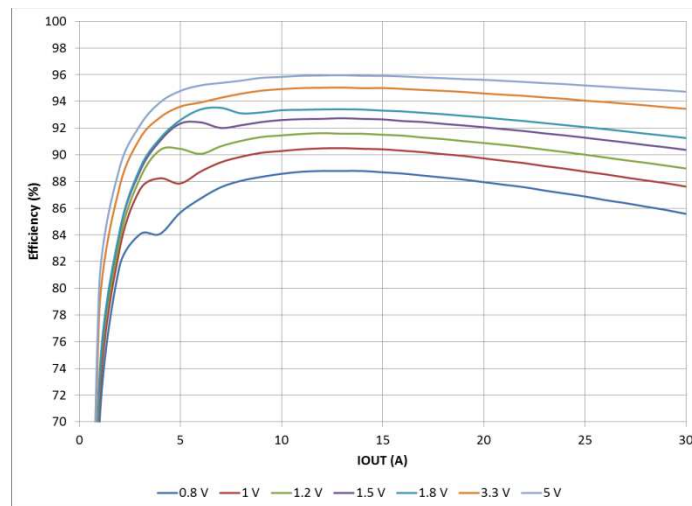
The Mean, min and max within each plot represent the variability in the SVID reading on a single part, due to noise. The table below provides a summary of measurement gain and offset taken on a statistically significant sample of parts.

	Gain	Offset
Average	0.954	0.137
Standard deviation	0.019	0.257
Min	0.919	-0.465
Max	1.009	0.95

TYPICAL EFFICIENCY AND POWER LOSS CURVES

$P_{Vin} = V_{in} = 12V$, $V_{CC} = 5V$, $I_o=0-30A$, $F_s= 600kHz$, Room Temperature, No Air Flow. Note that the losses of the inductor, input and output capacitors are also considered in the efficiency and power loss curves. The table below shows the indicator used for each of the output voltages in the efficiency measurement.

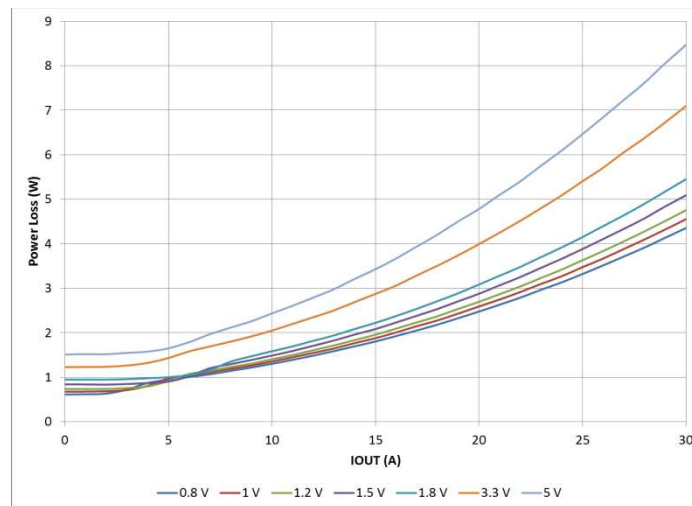
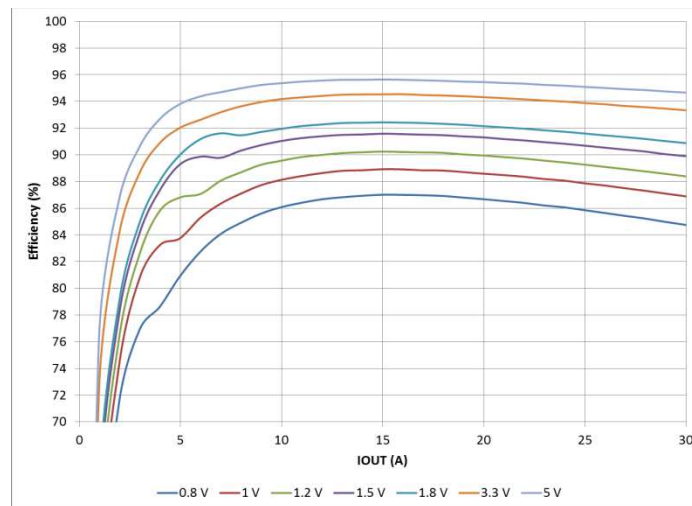
V _{OUT} (V)	L _{OUT} (μH)	P/N	DCR (mΩ)
0.8	0.15	HCB138380D-151 (Delta)	0.15
1	0.15	HCB138380D-151 (Delta)	0.15
1.2	0.15	HCB138380D-151 (Delta)	0.15
1.5	0.15	HCB138380D-151 (Delta)	0.15
1.8	0.15	HCB138380D-101 (Delta)	0.15
3.3	0.32	FP1308R3-R32-R (Cooper)	0.32
5	0.32	FP1308R3-R32-R (Cooper)	0.32



TYPICAL EFFICIENCY AND POWER LOSS CURVES

PVin = Vin = 12V, Internal LDO, Io=0-30A, Fs= 600kHz, Room Temperature, No Air Flow. Note that the losses of the inductor, input and output capacitors are also considered in the efficiency and power loss curves. The table below shows the indicator used for each of the output voltages in the efficiency measurement.

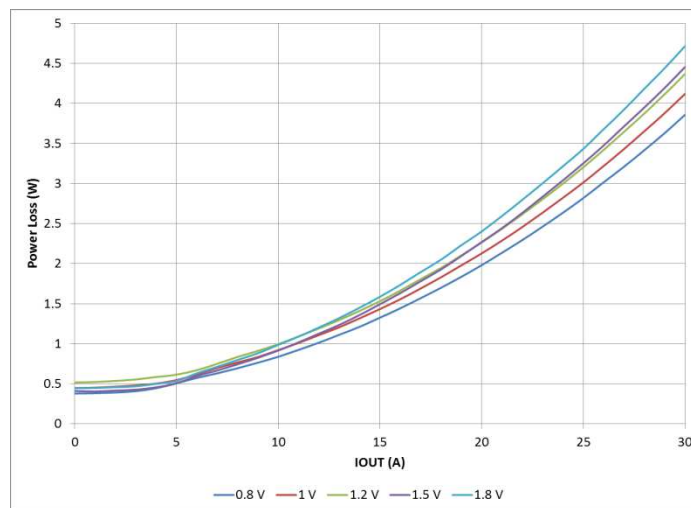
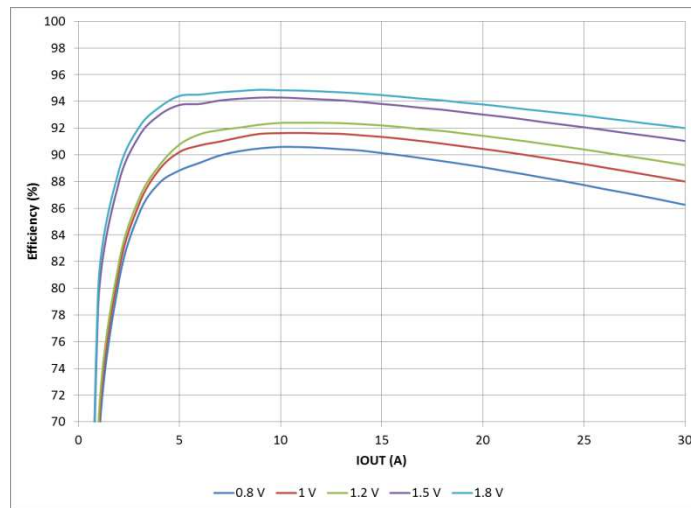
VOUT (V)	LOUT (μH)	P/N	DCR (mΩ)
0.8	0.15	HCB178380D-151 (Delta)	0.15
1	0.15	HCB138380D-151 (Delta)	0.15
1.2	0.15	HCB138380D-151 (Delta)	0.15
1.5	0.15	HCB138380D-151 (Delta)	0.15
1.8	0.15	HCB138380D-101 (Delta)	0.15
3.3	0.32	FP1308R3-R32-R (Cooper)	0.32
5	0.32	FP1308R3-R32-R (Cooper)	0.32



TYPICAL EFFICIENCY AND POWER LOSS CURVES

$P_{Vin} = V_{in} = V_{CC} = 5V$, $I_o=0-30A$, $F_s= 600kHz$, Room Temperature, No Air Flow. Note that the losses of the inductor, input and output capacitors are also considered in the efficiency and power loss curves. The table below shows the inductor used for each of the output voltages in the efficiency measurement.

V _{OUT} (V)	L _{OUT} (μH)	P/N	DCR (mΩ)
0.8	0.1	HCB138380D-101 (Delta)	0.15
1	0.1	HCB138380D-101 (Delta)	0.15
1.2	0.15	HCB138380D-101 (Delta)	0.15
1.5	0.15	HCB138380D-151 (Delta)	0.15
1.8	0.15	HCB138380D-151 (Delta)	0.15



THEORY OF OPERATION

DESCRIPTION

The IR38163 and IR38165 are 30A rated synchronous buck converters that support PMBus and I2C digital interfaces respectively. The IR38363 and IR38365 are the corresponding 15A rated versions. All the four devices in this family of OPTIMOS IPOL devices are Intel SVID compliant and can support VR12.5 as well as VR13. They use an externally compensated fast, analog, PWM voltage mode control scheme to provide good noise immunity as well as fast dynamic response in a wide variety of applications. At the same time, the digital communication interfaces allow complete configurability of output setting and fault functions, as well as telemetry.

The switching frequency is programmable from 150 kHz to 1.5 MHz and provides the capability of optimizing the design in terms of size and performance. It is recommended to operate at 500 kHz or higher.

These devices provide precisely regulated output voltages from 0.5V to $0.875 \cdot P_{Vin}$ programmed via two external resistors or through the communication interfaces. They operate with an internal bias supply (LDO), typically 5.2V. This allows operation with a single supply. The output of this LDO is brought out at the Vcc pin and must be bypassed to the system power ground with a 10 uF decoupling capacitor. The Vcc pin may also be connected to the Vin pin, and an external Vcc supply between 4.5V and 5.5V may be used, allowing an extended operating bus voltage (P_{Vin}) range from 1.5V to 16V.

The device utilizes the on-resistance of the low side MOSFET (synchronous MOSFET) as current sense element. This method enhances the converter's efficiency and reduces cost by eliminating the need for external current sense resistor.

These devices includes two low $R_{ds(on)}$ MOSFETs using Infineon's OptiMOS technology. These are specifically designed for low duty cycle, high efficiency applications.

DEVICE POWER-UP AND INITIALIZATION

During the power-up sequence, when Vin is brought up, the internal LDO converts it to a regulated 5.2V at Vcc. There is another LDO which further converts this down to 1.8V to supply the internal digital circuitry. An under-voltage lockout circuit monitors the voltage of VCC pin and the P1V8 pin, and holds the Power-on-reset (POR) low until these voltages exceed their thresholds and the internal 48 MHz oscillator is stable. When the device comes out of reset, it initializes a multiple times programmable (MTP) memory load cycle, where the contents of the MTP are loaded into the working registers. Once the registers are loaded from MTP, the designer can use PMBus commands to re-configure the various parameters to suit the specific VR design requirements if desired, irrespective of the status of Enable.

The typical default configuration utilizes the internal LDO to supply the VCC rail when P_{Vin} is brought up. For this configuration power conversion is enabled only when the Enable pin voltage exceeds its under voltage threshold, the P_{Vin} bus voltage exceeds its under voltage threshold, the contents of the MTP have been fully loaded into the working registers and the device address has been read. The initialization sequence is shown in Figure 8. Another common default configuration uses an external power supply for the VCC rail. While in this configuration it is recommended to ensure the VCC rail reaches its target voltage prior the enable signal goes high.

Additional options are available to enable the device power conversion through software and these options may be configured to override the default by using the I2C interface or PMBus. For further details see the UN0075 IR3816x_IR3826x_IR3836x_PMBus commandset user note.

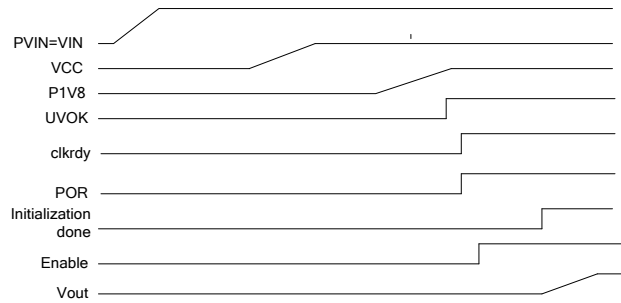


Figure 8: Initialization sequence showing PVin, Vin, Vcc, 1.8V, Enable and Vout signals as well as the internal logic signals

I2C AND PMBUS COMMUNICATION

All the devices in this family have two 7-bit registers that are used to set the base I2C address and base PMBus address of the device, as shown below in Table 1.

Table 1: Registers used to set device base address

Register	Description
I2c_address[6:0]	The chip I2C address. An address of 0 will disable I2C communication. Note that disabling I2C does not disable PMBus.
Pmbus_address[6:0]	The chip PMBus address. An address of 0 will disable PMBus communication. Note that disabling PMBus does not disable I2C.

In addition, a resistor may be connected between the ADDR and LGND pins to set an offset from the default preconfigured I2C address (0x10) /PMBus address (0x40) in the MTP. Up to 16 different offsets can be set, allowing 16 devices with unique addresses in a single system. This offset, and hence, the device address, is read by the internal 10 bit ADC during the initialization sequence.

Table 2 below provides the resistor values needed to set the 16 offsets from the base address.

Table 2 : Address offset vs. External Resistor(R_{ADDR})

ADDR Resistor (Ohm)	Address Offset
499	+0